

Electronic Acknowledgement Receipt

EFS ID:	8708362
Application Number:	10802566
International Application Number:	
Confirmation Number:	3507
Title of Invention:	High performance IC chip having discrete decoupling capacitors attached to its IC surface
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Patricia Balero
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0109
Receipt Date:	26-OCT-2010
Filing Date:	17-MAR-2004
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Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$ 180
RAM confirmation Number	5981
Deposit Account	502624
Authorized User	

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Charge any Additional Fees required under 37 C.F.R. Section 1.21 (Miscellaneous fees and charges)

File Listing:					
Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureState ment1-085027-0109.pdf	169672	no	3
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Warnings:					
Information:					
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2	NPL Documents	0557TW_Office_Action_10_08_2009_pdf.pdf	1506201	no	12
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3	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureState ment2-085027-0109.pdf	186451	no	5
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4	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221	no	4
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5	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109	no	9
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6	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666	no	7
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7	NPL Documents	4_GAO_An_improved_electros tatic_discharge_protection_str ucture.pdf	885848	no	6
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8	NPL Documents	5_YOEH_Copper_Die_Bumps. pdf	717153	no	5
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9	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f30badcc448865be25da92121b117fce267a05	no	7
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Information:					
10	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8132037f7462423e7e041a4f39e24a5e4578ab27	no	8
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11	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a726022251835f4d292326de7bc282d59441d614	no	4
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12	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab71bc6a4d8720a9b8f6ef9476e4dc5e395eebb5	no	4
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13	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 9501660bd4c4309f18b1797ed0026a7b2bcd14322	no	4
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16	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGE_BiCMOS_process.pdf	420788 8e26f2f669459e3ce07d15bd587c4a335999fa0e	no	4
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17	NPL Documents	14_SAKRAN_implementation_of_65nm.pdf	1254646 3b466f954664fc7184e7330836837d22ae08c5a1	no	3
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18	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 c0afedaf905c311c1fc91a55df92d1793f8f437f	no	2
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28	NPL Documents	25_PDF_LIN_A_New_System_ On_Chip_Technology_pdf_pdf. pdf	390082	no	7
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Information:					
Total Files Size (in bytes):			42668302		

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.